

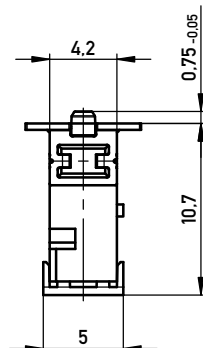
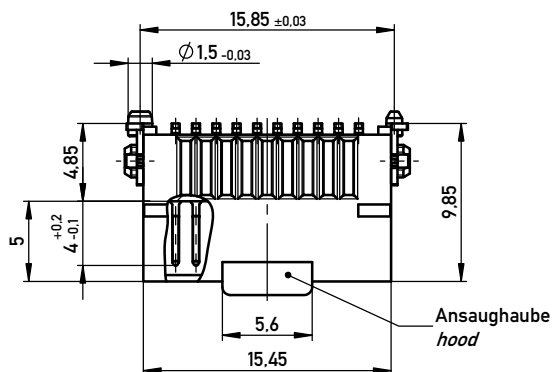
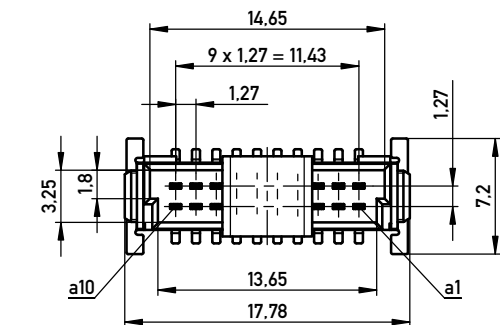
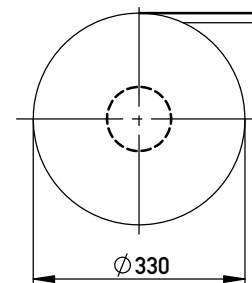
Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

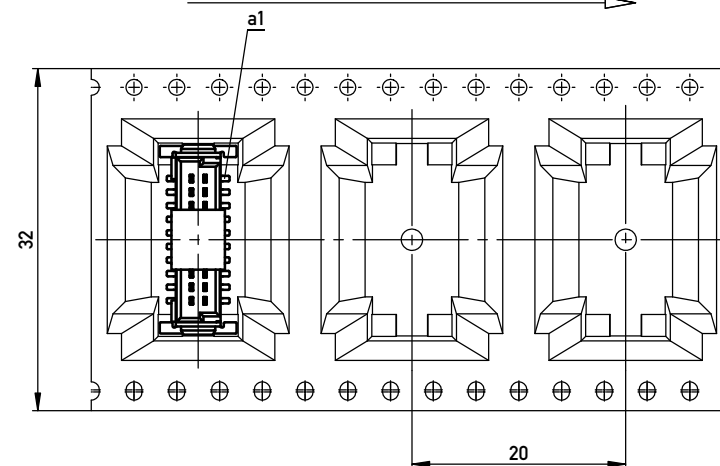
Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
Coplanarity Area of Termination ≤ 0,1 mm

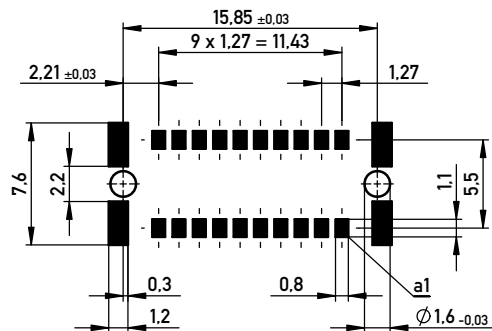
Verpackt im Gurt nach DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 250 Stück
Packaging unit: 250 pcs



Abspulrichtung - Reel off Direction



Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



BA 8-23 - hohe Bauhöhe

type 8-23 - High Profile

Information:		Tolerances		Scale	3:1
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e		26.06.2015		Messerl. SMC-Q 20-SMD-BA8-23	
Index		Date		Male SMC-Q 20-SMD-type8-23	
		ERNI www.ERNI.com		254415	
				I	
				A3	
				Class	
				SMCQ	

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